

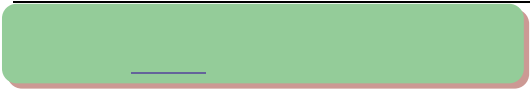


有铅

Sn63/Pb37 Sn60/Pb40, Sn55Pb45, SnPbBi

- 1 0.2mm
- 2 12
- 3
- 4
- 5
- 6 PCB
- 7 ICT
- 8 ----- Paste in hole -----

| | | | |
|-------|---------|---------------------------------|-----------------------------|
| | | | |
| | | ROL1 | J-STD-004 |
| 卤素 | 0.15wt% | | |
| (SIR) | | 1×10^{13} | 25mil |
| | | 1×10^{12} | 40 90%RH 96Hrs |
| | | 1×10^5 | |
| | | | IPC-TM-650 |
| | | | IPC-TM-650 |
| | | | In house |
| | | | |
| | | 85~91wt% ± 0.5 | |
| | | 9~15wt% ± 0.5 | |
| | | 220 ±30 Pa.s Malcolm (10rpm,2) | T5,89% metal for printing |
| | | 160 Pa.s±10% Malcolm (10rpm,2) | T4,87% metal for syringe |
| | | 0.55 ± 0.05 | In house |
| | | 90% | Copper plate(Sn63,90%metal) |
| | | | J-STD-005 |
| | | | In house |
| Vs | 48gF | 0 | IPC-TM-650 ± 5% |
| | 56gF | 2 | |
| | 68gF | 4 | |
| | 44gF | 8 | |
| | | 12 | In house |
| | | | 0~10 |
| | | | |



1

T3 mesh -325/+500 25~45μ m

Fine pitch

2

1) “ ”

0~10

200

4

2)

3

1 ;

3



有铅免洗

0.4mm

0.12mm



有铅免洗

80%

| | |
|--|--|
| | 60 ~ 90HS |
| | 45 ⁰ ~ 60 ⁰ |
| | 2 ~ 4 × 10 ⁵ pa |
| | 20 ~ 40mm/sec 15 ~ 20mm/sec 50 ~ 100mm/sec |
| | 25 ± 3 40 ~ 70% |



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PCB

PCB

A5

200g

B5

300g

A4

400g

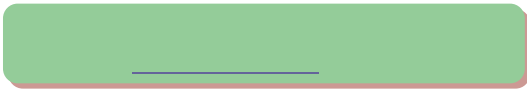
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4

5

6

此有铅



500g

PE

20

35



0 ~10

•

•

0

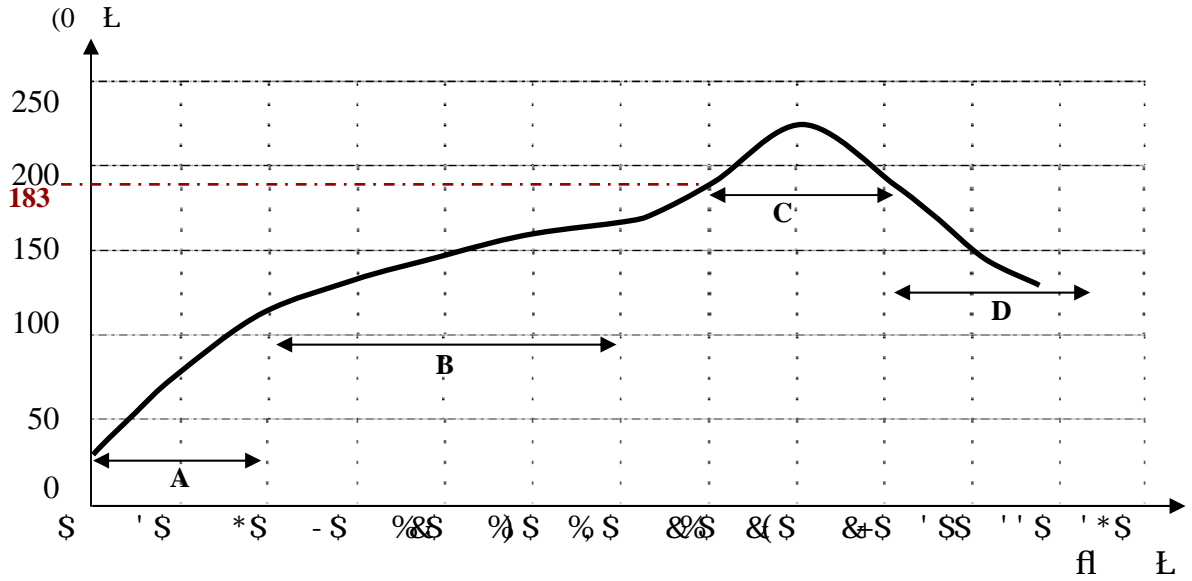
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MSDS

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Sn63/Pb37 Sn60/Pb40, Sn55Pb45, SnPbBi



A. 25~33%

* 1.0~3.0 /
*

B. 33~50%

* 130~170 60~120 2 /
PCB

C.

* 210~240 183 40~90 Important 200 20~50
*
*

D.

* 4 75
*
*

-
-
-